

FIG. 1A

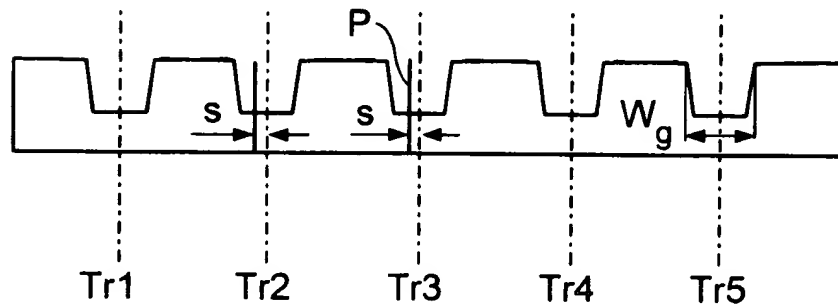


FIG. 1B

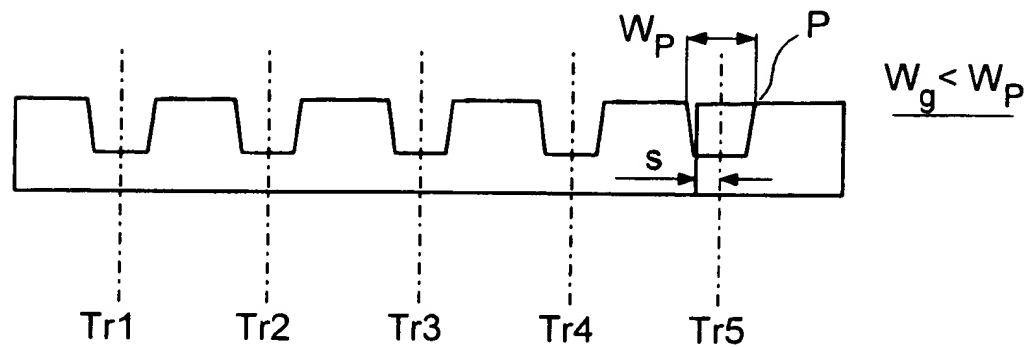


FIG. 1C

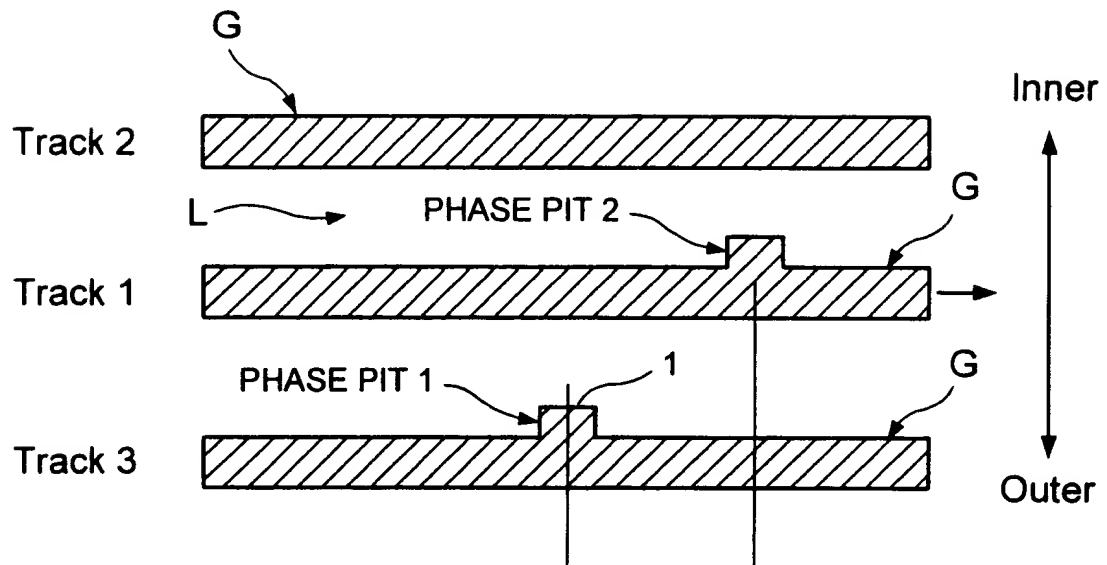


FIG. 2A

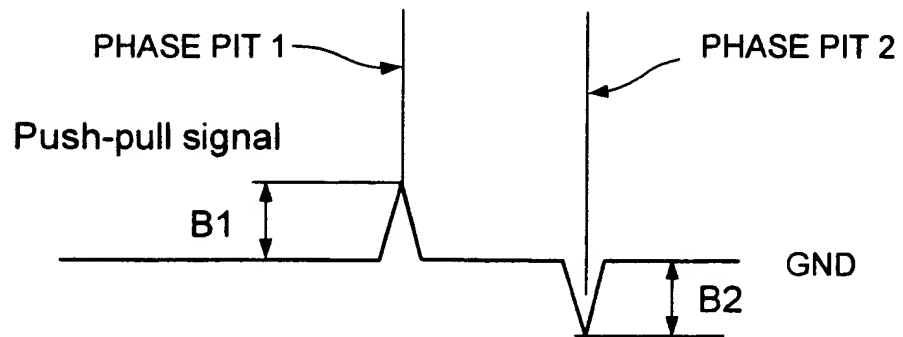


FIG. 2B

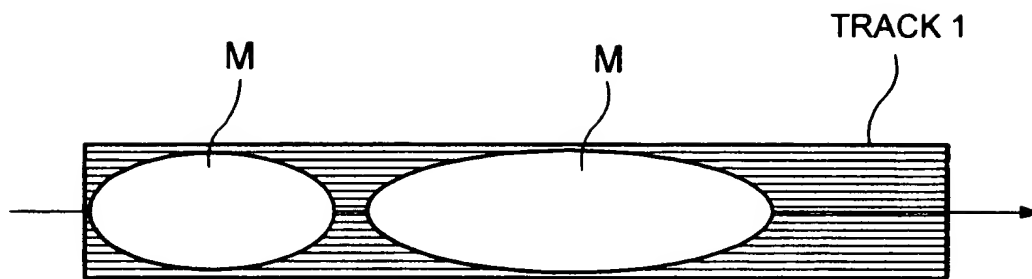


FIG. 3A

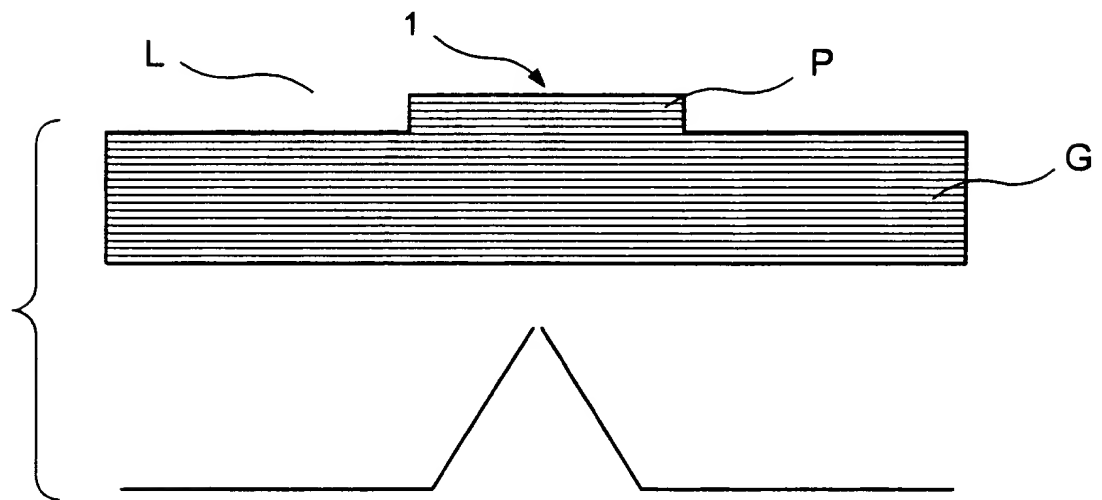


FIG. 3B

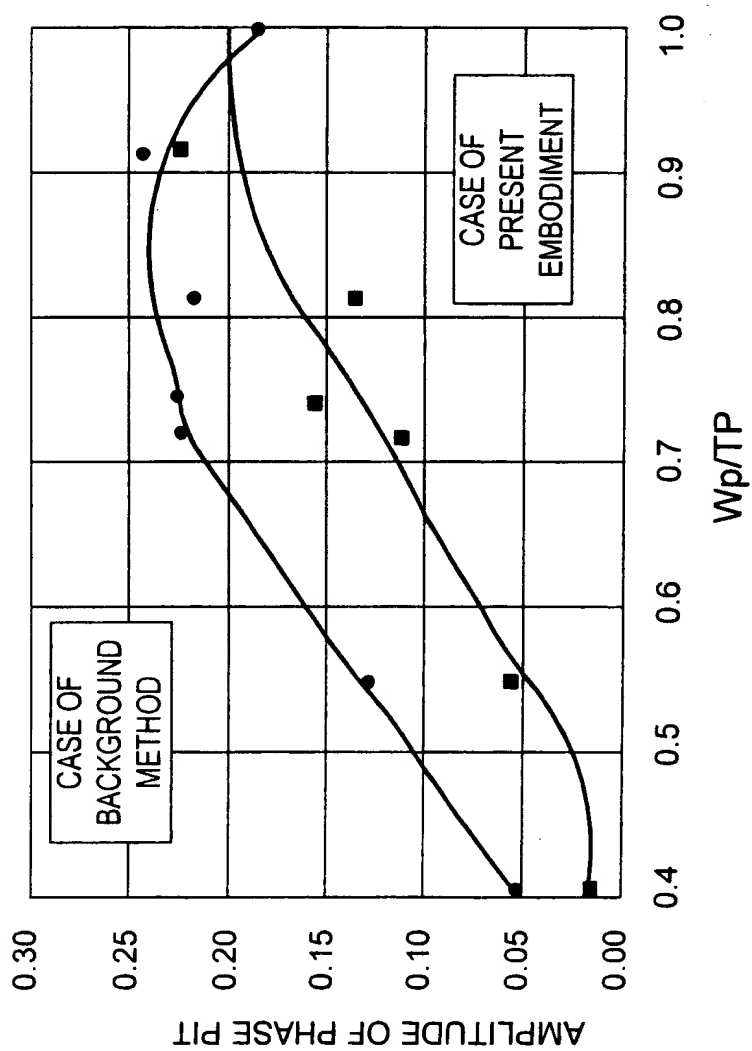
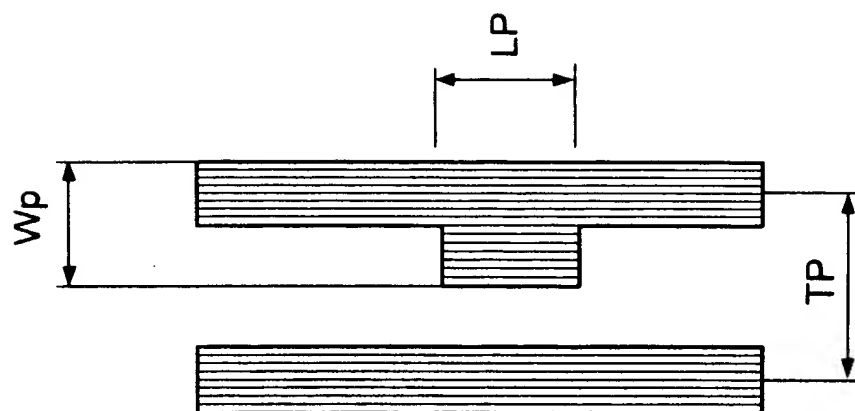


FIG. 4

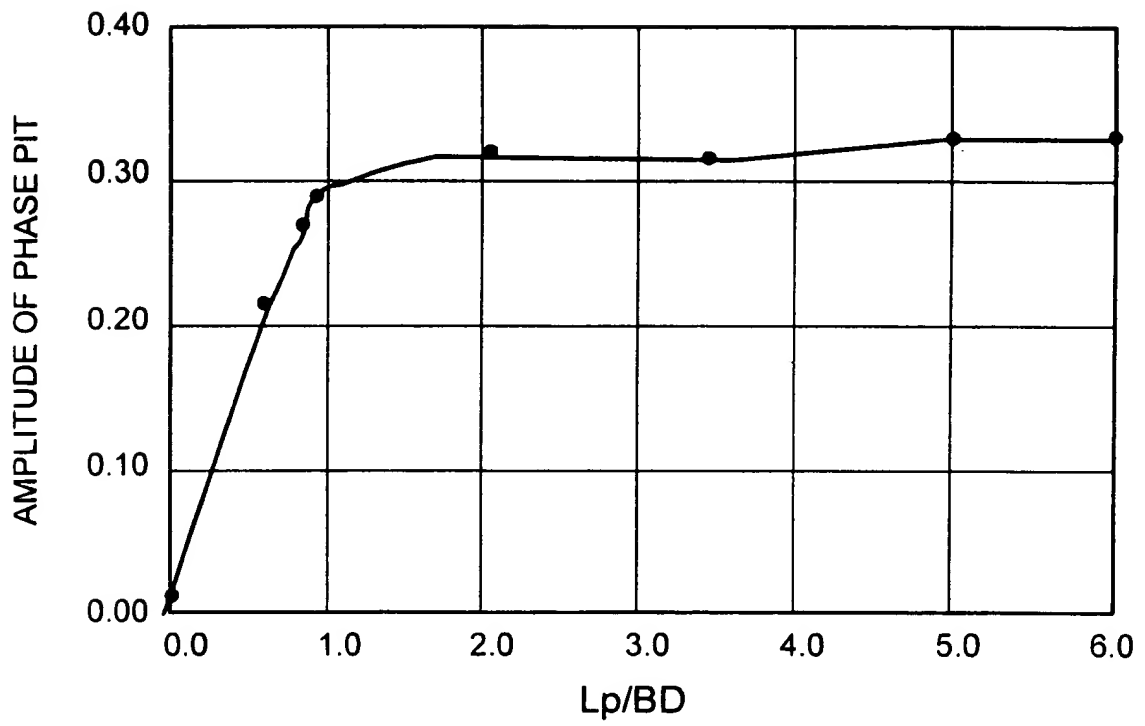


FIG. 5

FIG. 6A

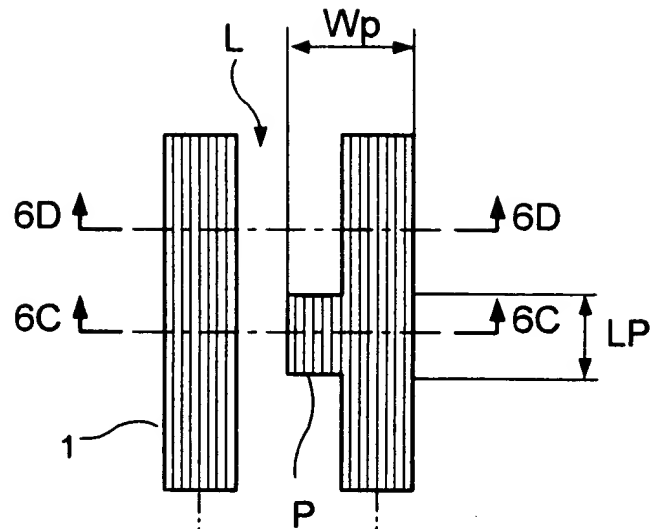


FIG. 6B

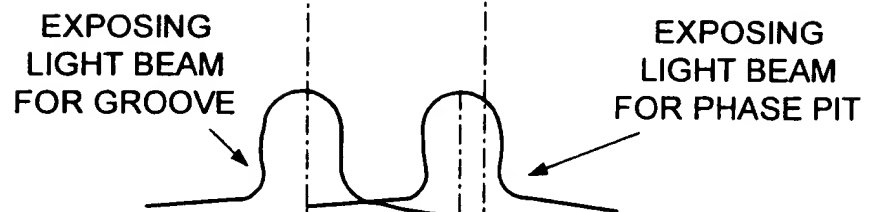


FIG. 6C

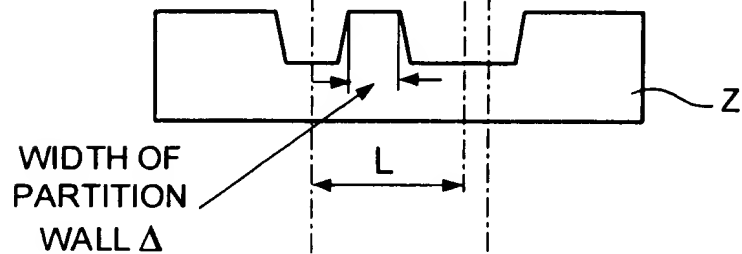
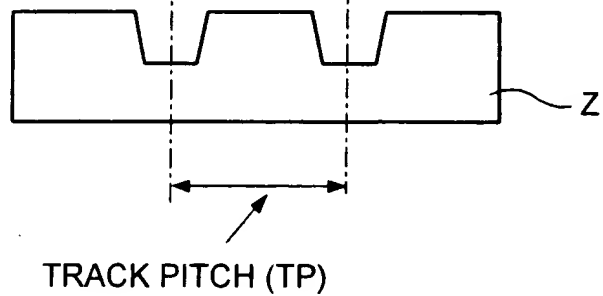


FIG. 6D



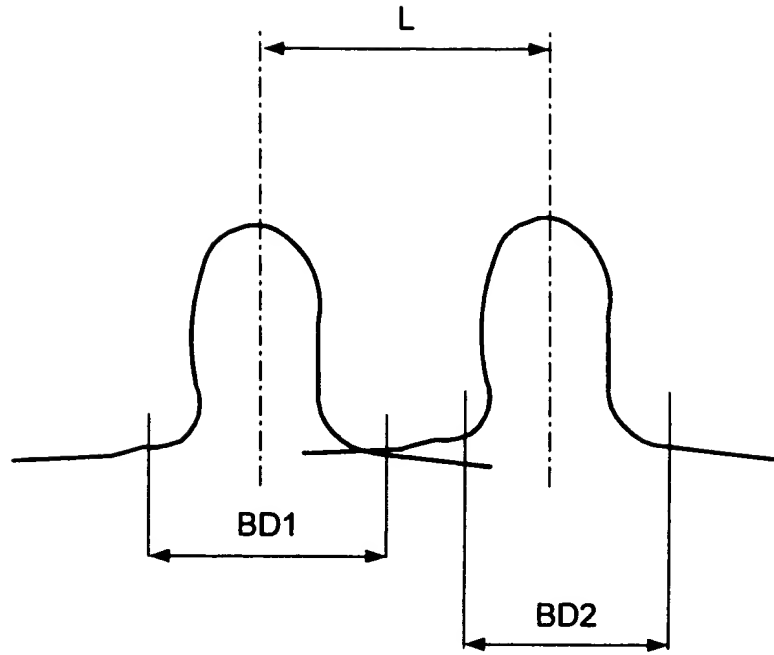


FIG. 7

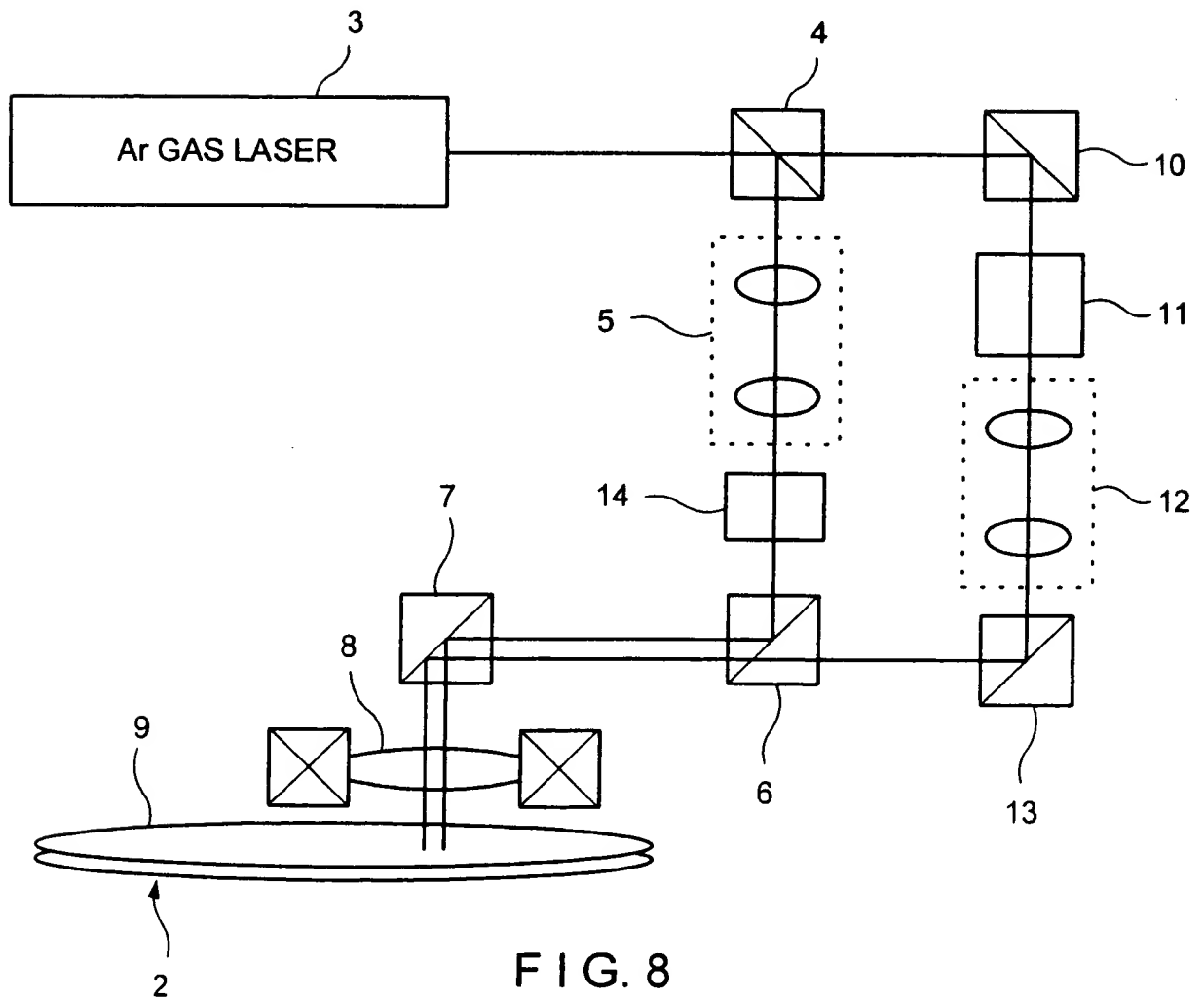


FIG. 8

FIG. 9A

MAKING OF RESIST
ORIGINAL BOARD

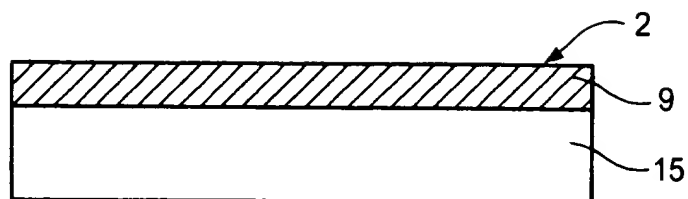


FIG. 9B

EXPOSING OF
ORIGINAL BOARD

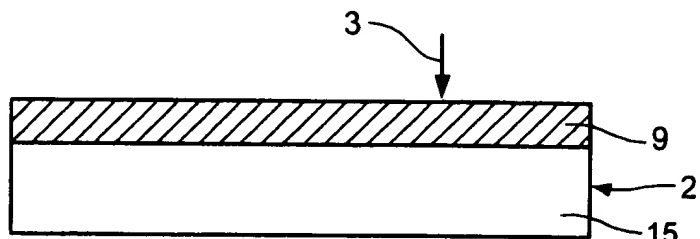


FIG. 9C

DEVELOPING

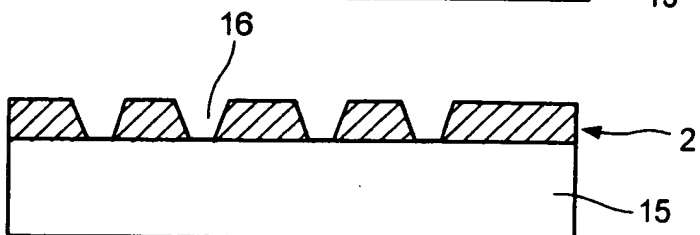


FIG. 9D

PROCESSING OF
CONDUCTIVE FILM



FIG. 9E

NI ELECTROFORMING

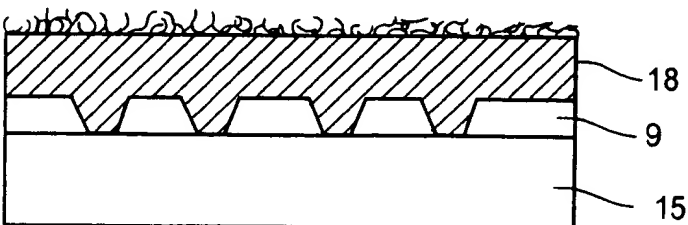
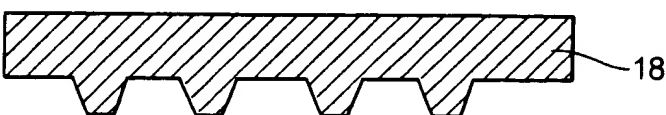


FIG. 9F

PEELING-OFF
CLEANING
POLISHING OF REAR SURFACE
FINAL PROCESSING



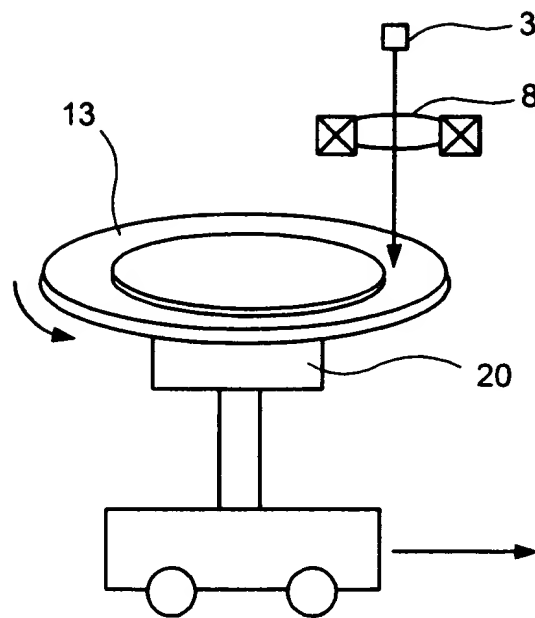
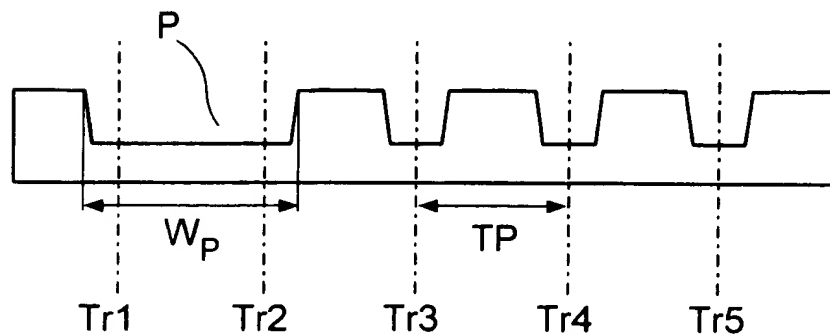
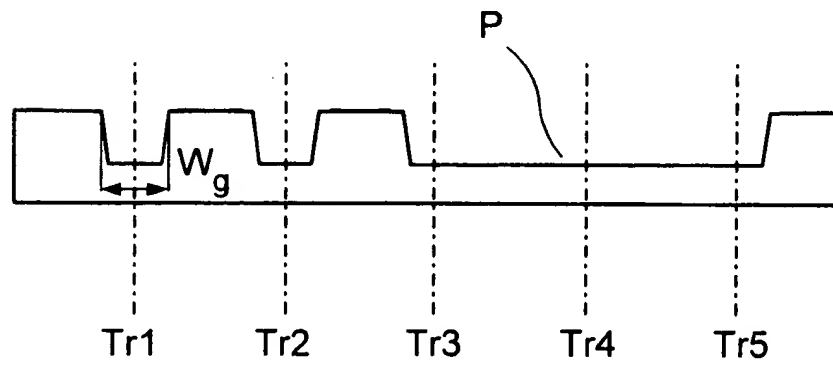
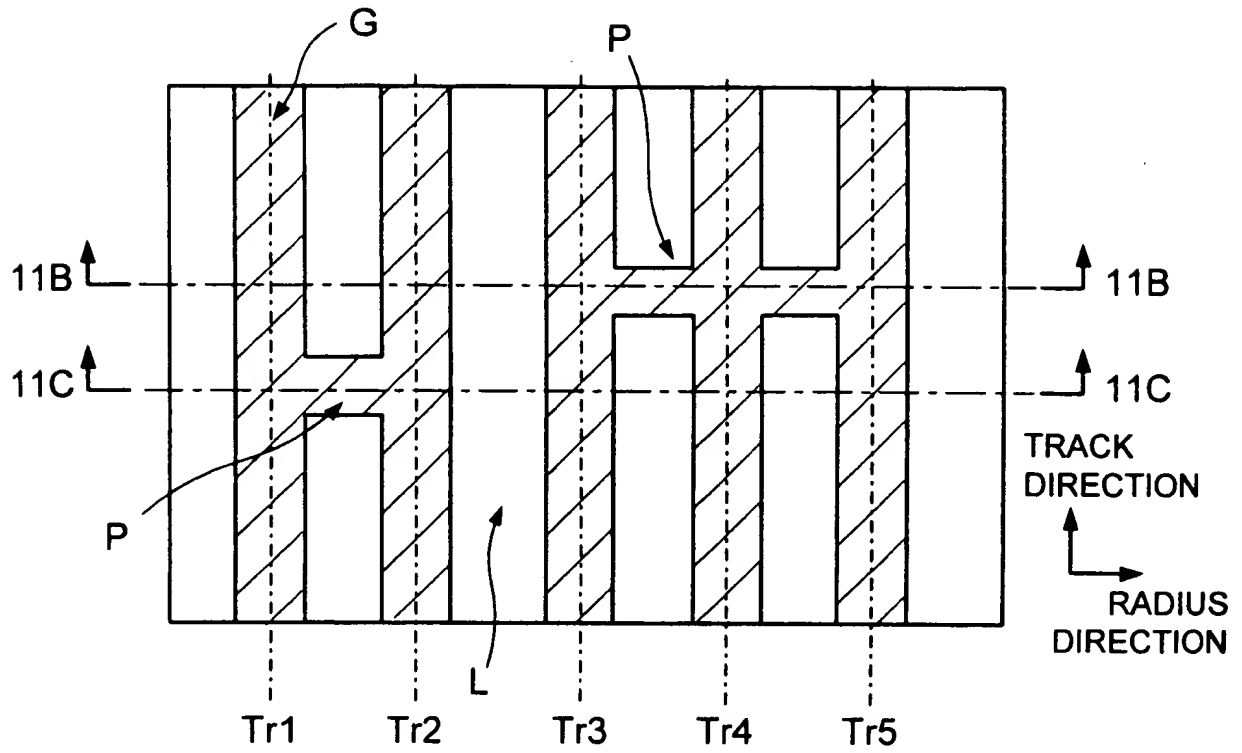


FIG. 10



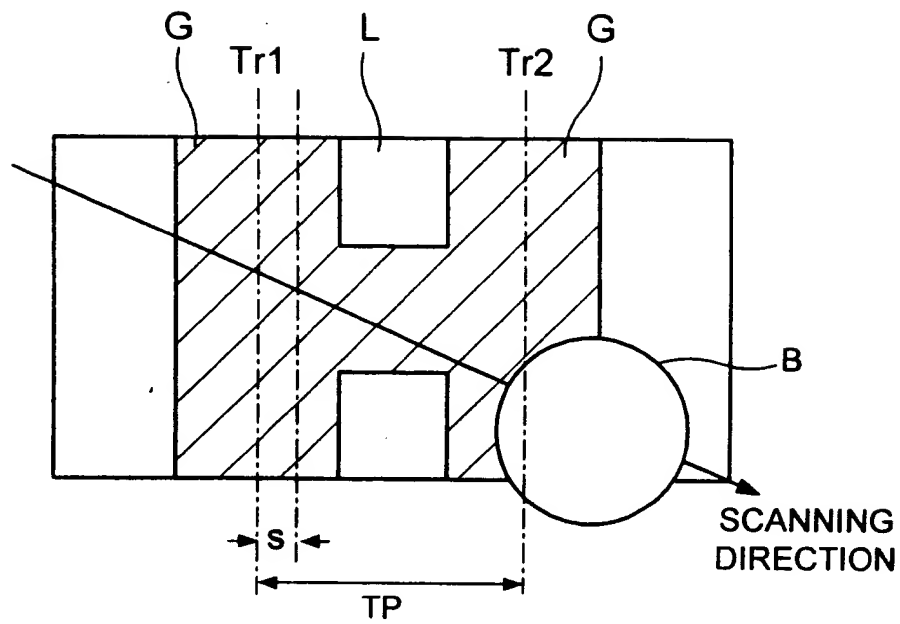


FIG. 12A

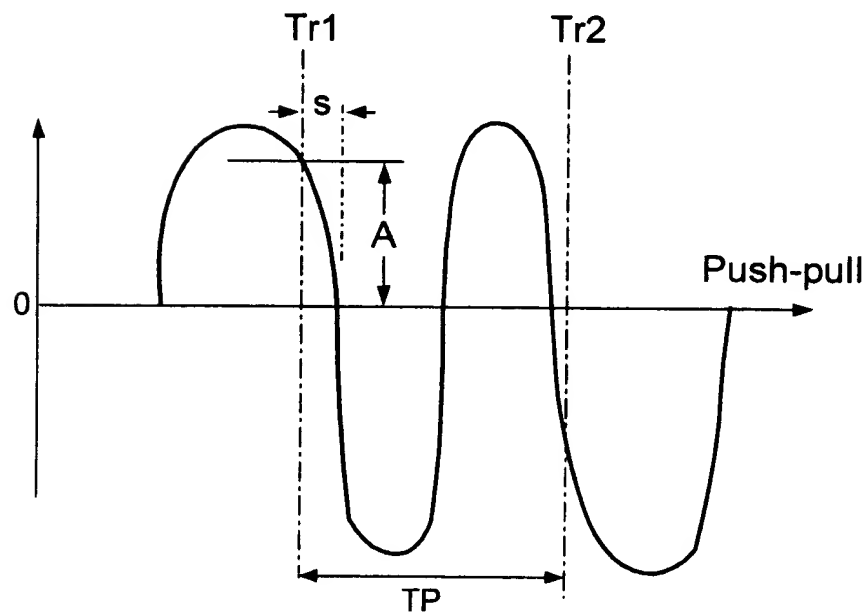


FIG. 12B

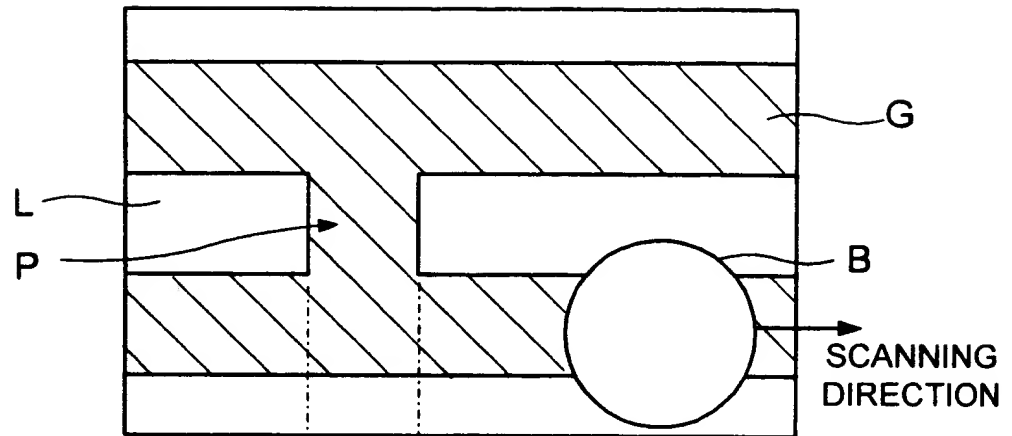


FIG. 13A

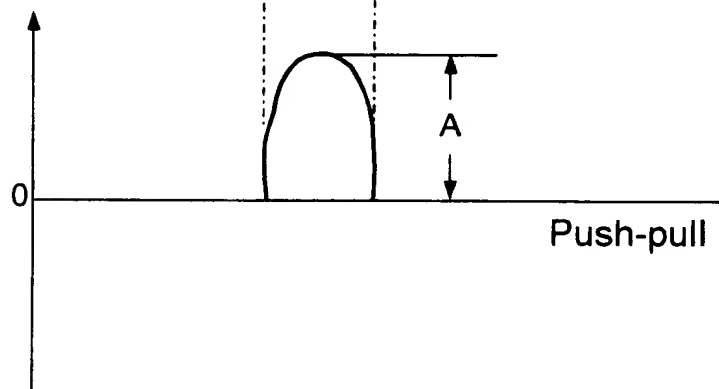


FIG. 13B

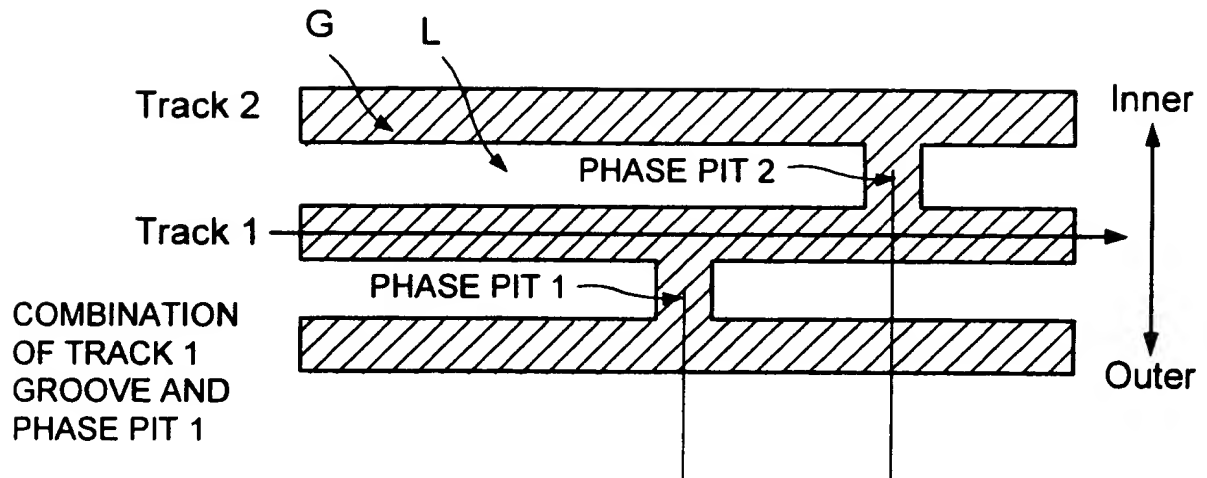


FIG. 14A

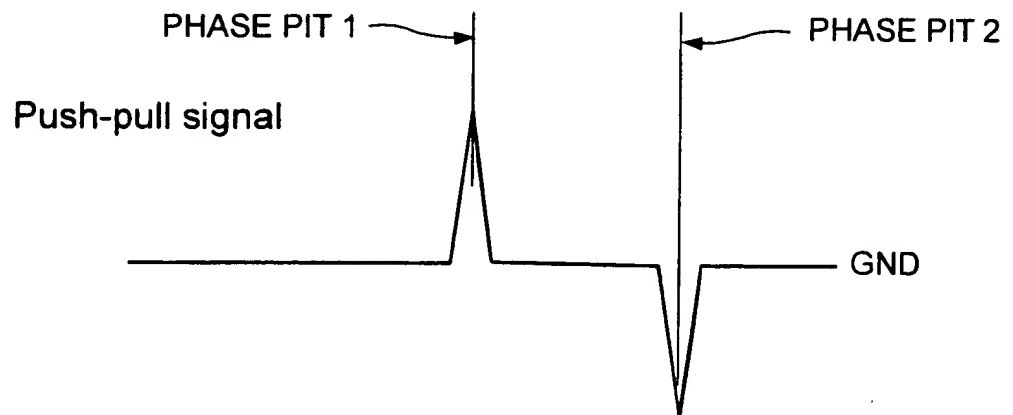


FIG. 14B

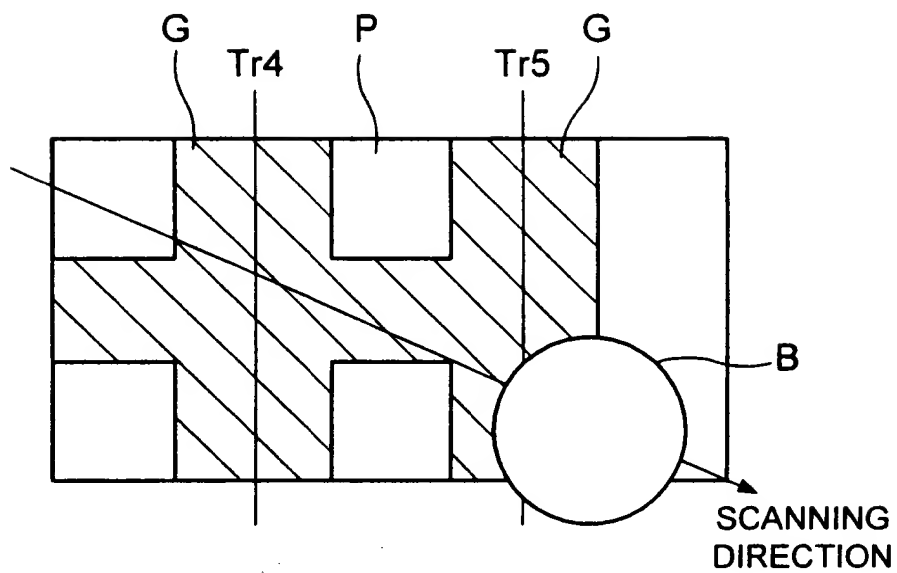


FIG. 15A

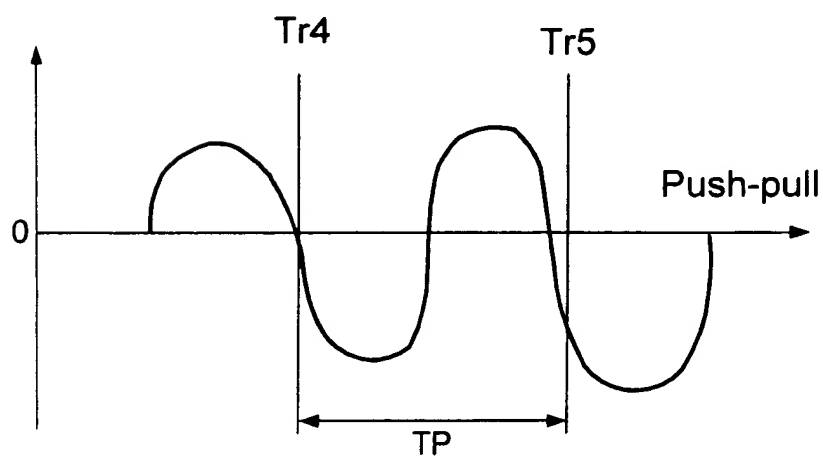


FIG. 15B

FIG. 16A

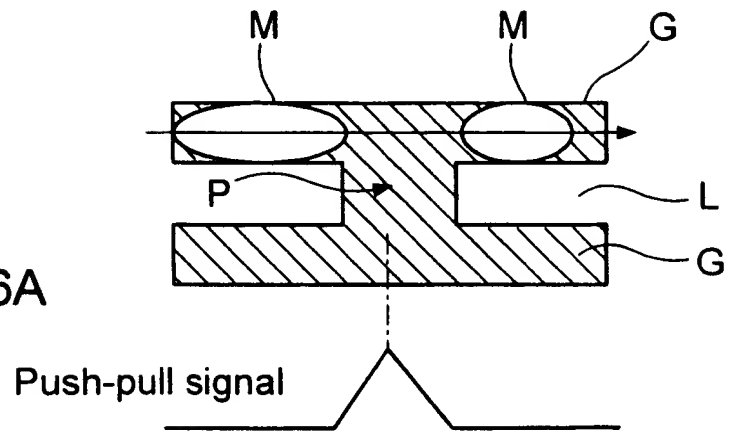


FIG. 16B

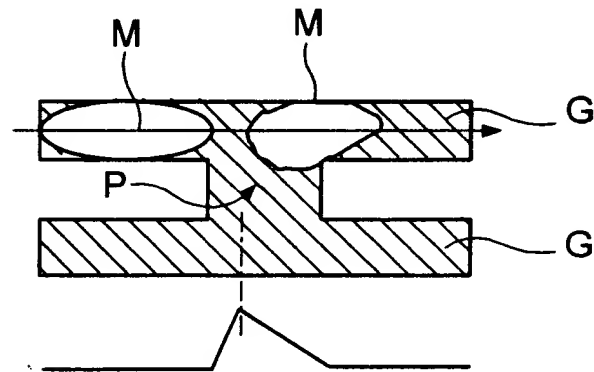


FIG. 16C

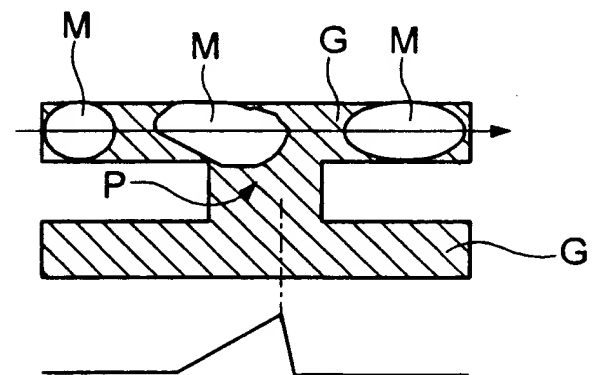
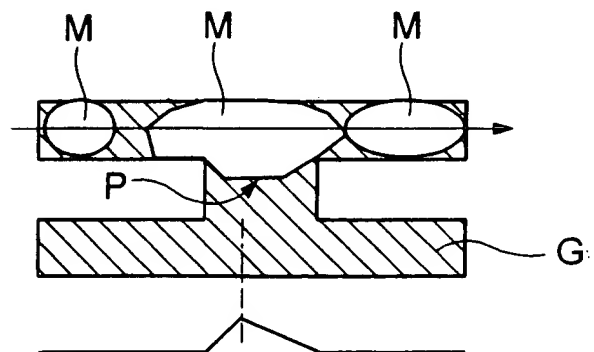


FIG. 16D



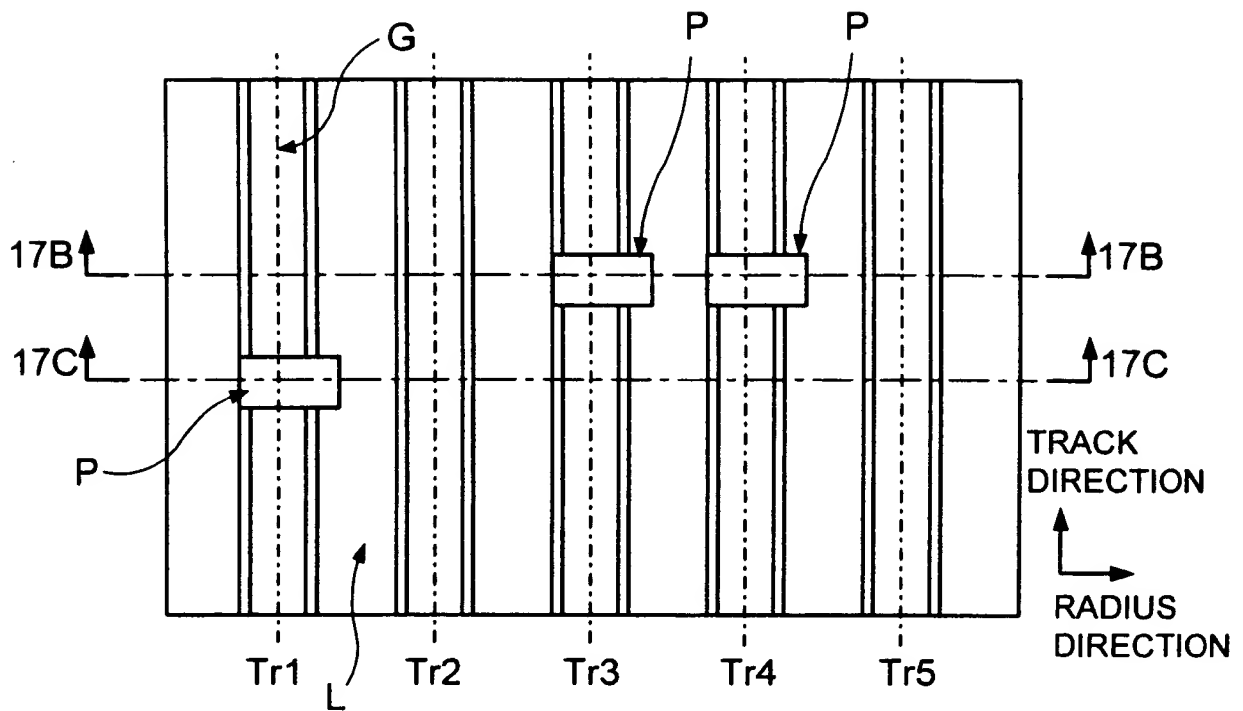


FIG. 17A
PRIOR ART

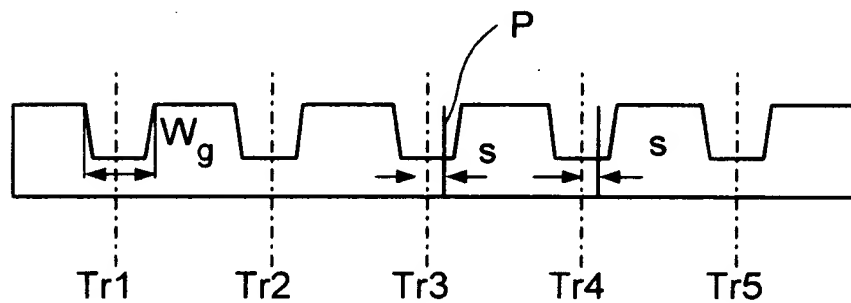


FIG. 17B
PRIOR ART

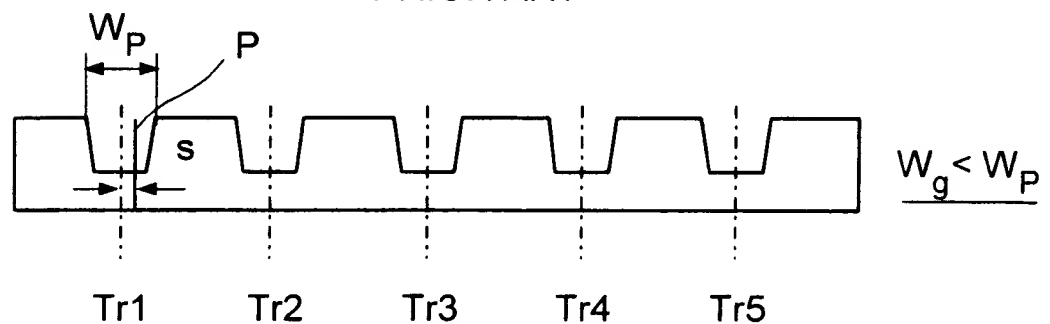


FIG. 17C
PRIOR ART

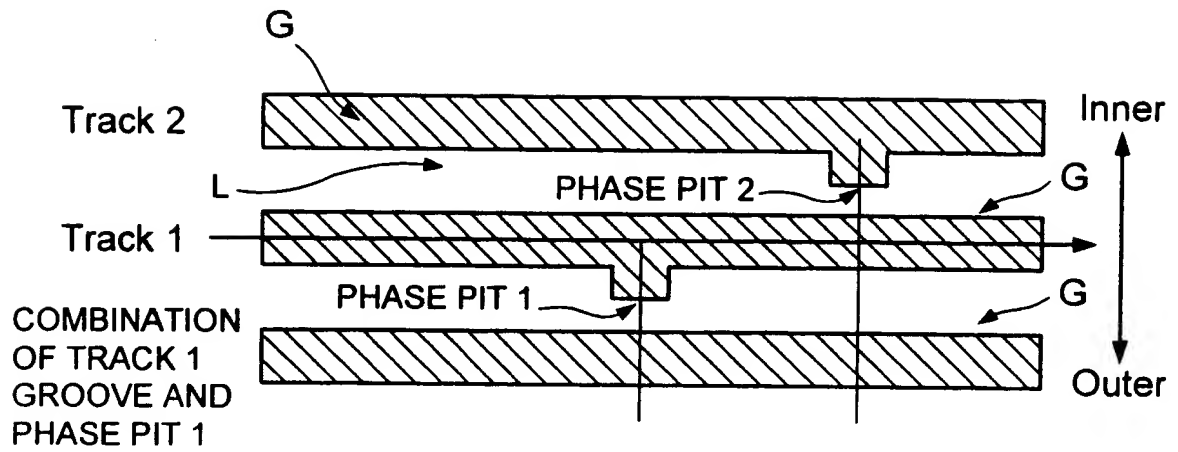


FIG. 18A
PRIOR ART

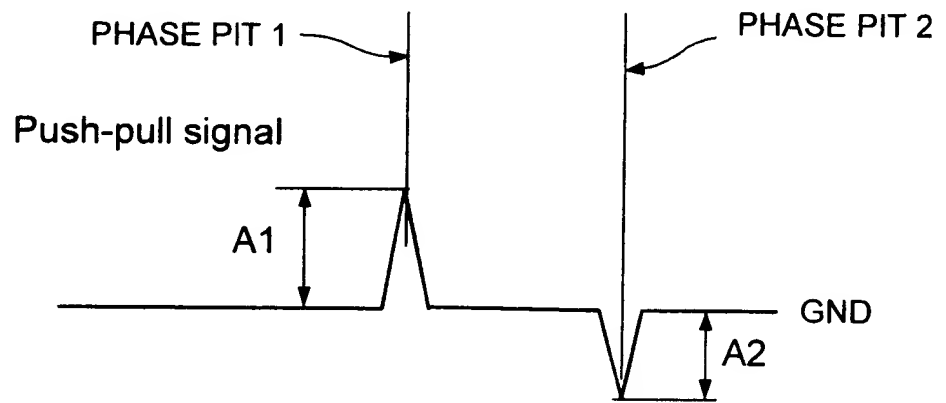


FIG. 18B
PRIOR ART